



The Strategies of COTS Components on Selection, Validation and Usage and Some Typical Applications in Space Missions

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- ❑ Instruction
- ❑ Selection Strategies of COTS Components
- ❑ Validation Methods for COTS Components
- ❑ Application Hardening Techniques
- ❑ Typical Application Case
- ❑ Summary

- **COTS Adoption in Space**

- Commercial aerospace demand drives high-performance, low-cost COTS integration
- E.g., SpaceX, China's Thousand Sail Constellation.

- **Challenges and Opportunities**

- **Market Dynamics:** Aerospace-grade components trade volume <0.2% of global semiconductor market.
- **Performance Gap:** Radiation-hardened (RH) components lag COTS by >10 years in processor performance.
- **Key Drivers:** Cost reduction, rapid development cycles, and scalability for mass production.

2.1 Requirement Analysis

- **Functional Performance:** Match mission requirements (e.g., power, interfaces, redundancy).
- **Environmental Adaptability:** Assess temperature range, radiation, vacuum, mechanical stress, etc.
- **Quality & Reliability:** Lifetime, failure rate, failure modes.

2. Selection Strategies of COTS Components

2.2 COTS Component Product Selection

Category	Selection Element	Description
Inherent Characteristics	Function	<ul style="list-style-type: none"> • Ensure selected COTS components align with mission objectives. • Verify compatibility with peripheral circuits (power supply, drive circuits). • Assess industrial maturity of the overall circuit design and redundancy backup strategies.
	Performance	<ul style="list-style-type: none"> • Require technical/test data to confirm performance meets mission specifications. • Prioritize components with stable parameter values under extreme operating temperatures.
	Package	<ul style="list-style-type: none"> • Select packaging forms compatible with mature electrical assembly processes. • Avoid high-density assembly processes or restricted materials (e.g., lead-free coatings).
	Development tool	<ul style="list-style-type: none"> • Ensure availability of debugging tools (simulators, IDEs) and software libraries (OS, algorithms). • Validate the external interface of components, which can easily realize data.
Environmental adaptability	Temperature range	<ul style="list-style-type: none"> • Prioritize COTS components with the widest operational temperature range (vs. aerospace-grade counterparts).
	Environmental sensitivity	<ul style="list-style-type: none"> • Address risks like electrostatic/moisture sensitivity during installation, storage, and testing. • Implement preventive measures (e.g., shielding, controlled storage).
	Environment adaptability	<ul style="list-style-type: none"> • Assess adaptability to radiation, vacuum, mechanical stress, corrosion, and tin whisker risks. • Mitigate risks through material selection and design modifications.
Quality Reliability	Quality reliability	<ul style="list-style-type: none"> • Review screening reports, lot consistency, and failure rate data. • Validate supplier claims using sample tests for critical components. • Align component failure modes with mission reliability thresholds. • Conduct life-cycle testing for high-risk applications.

2.3 COTS supplier selection

Select elements	Description
Feasibility of cost and cycle	<ul style="list-style-type: none"> • Cost Analysis: <ul style="list-style-type: none"> • Evaluate historical purchase order data to assess cost-effectiveness (e.g., quality costs, sample losses). • Align testing cycles with mission timelines to avoid delays. • Optimization of delivery time: Prioritize suppliers with proven track records of on-time delivery.
Guarantee of stable supply	<ul style="list-style-type: none"> • Supply Chain Reliability: <ul style="list-style-type: none"> • Verify long-term availability of components during the mission lifecycle. • Ensure a backup plans for discontinued products (e.g., substitutes or stockpiling). • Storage and Replacement: Confirm compatibility of stored components with future functional requirements.
Stability of manufacturing process	<ul style="list-style-type: none"> • Process Consistency: <ul style="list-style-type: none"> • Assess impact of product/process changes on performance (e.g., material substitutions). • Require suppliers to notify changes affecting specifications. • Quality Assurance: Validate lot-to-lot consistency through third-party audits.
Timeliness of technical support	<ul style="list-style-type: none"> • Timely Technical Support: Ensure 24/7 access to technical support. • Rapid Issue Resolution: Ensure that problems are quickly resolved
Traceability of the development process	<ul style="list-style-type: none"> • Component Identification: <ul style="list-style-type: none"> • Track manufacturing sources via traceability codes (e.g., lot numbers, packaging week codes). • Validate authenticity using device/package box/inner packaging markings.

3.1 Validation Requirement Analysis

- **Pre-Validation Analysis:**
 - Review **application history**, lot quality data, and radiation resistance test results.
 - Assess historical quality issues and component selection necessity.
- **Component Specifications:**
 - Confirm component model, packaging, quality level, and product lot details.
 - Determine if **radiation resistance evaluation** or system-level hardening is required.
- **Action Plan:**
 - Conduct **part-level** or **board-level validation tests** based on analysis outcomes.

3.2 Part-Level Validation

- **Key Validation Steps:**
 - **Construction Analysis:**
 - **For Plastic Packaging:**
 - X-ray/C-SAM inspection, SEM analysis, bond strength tests.
 - Prohibited process checks (e.g., tin whiskers).
 - **For Ceramic Packaging:** Focus on material integrity and counterfeit detection.
 - **Radiation Resistance Evaluation:**
 - Perform **TID**, **SEE**, and **DD** tests.
 - **Additional Tests for New Components:**
 - Functional performance, simulated welding, limit testing, and lifecycle assessment.
- **Objective:** Identify prohibited processes, mitigate risks, and ensure aerospace suitability.

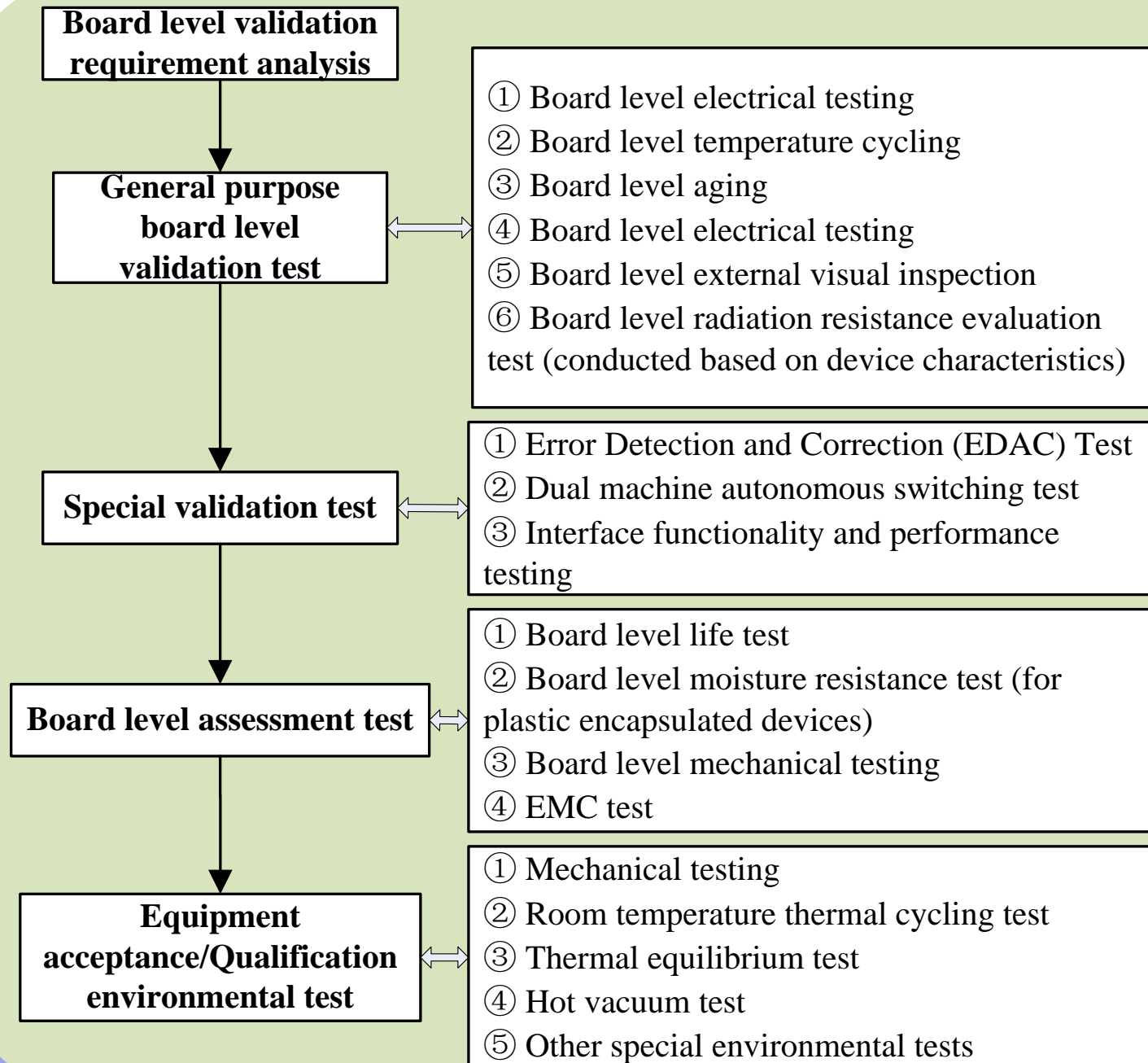
3.3 Board-Level Validation

Board-Level Validation Includes as follows:

- **General Purpose Testing:**
 - Temperature cycling, aging tests, visual inspection, and radiation resistance checks.
- **Specialized Testing:**
 - **EDAC validation**, dual-system switching, interface robustness testing.
- **Assessment Testing:**
 - Lifetime simulation, humidity resistance, mechanical stress, and EMC compliance.
- **acceptance/qualification testing of accompanying onboard-units or systems :**
 - Mechanic test, thermal cycle, thermal-vacuum test, etc.

3.3 Board-Level Validation

- **Validation Workflow:**
- **Key Strategies:**
 - Simplify part-level tests and integrate with board-level validation post-electrical assembly.
 - Try to combine onboard-units acceptance/qualification tests as much as possible.

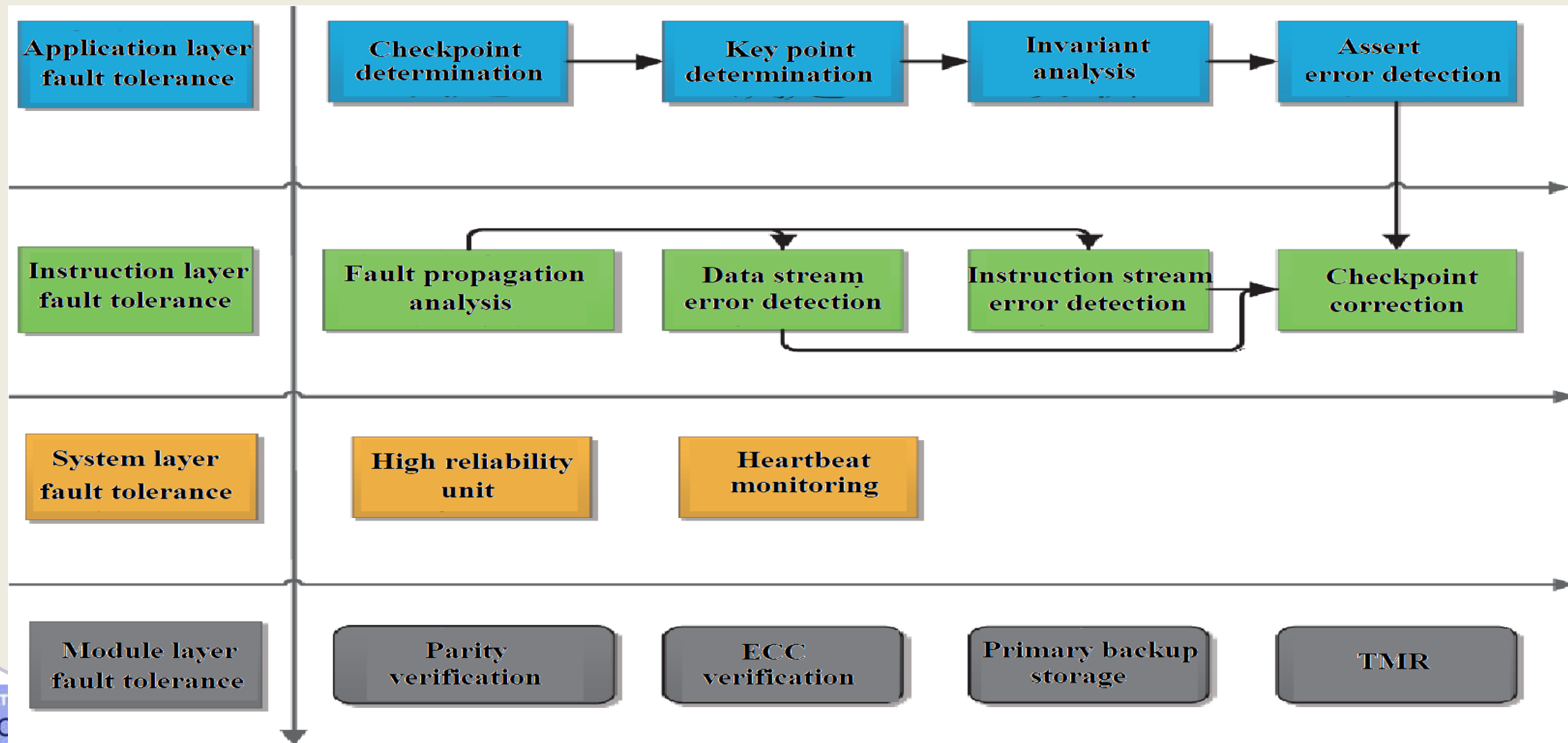


4.1 Common Application Hardening Methods

- **Fault Tolerance Design:**
 - **Watchdog Timers:** Monitor system health and trigger resets on failure.
 - **EDAC (Error Detection and Correction):** Correct memory errors caused by radiation.
 - **Dual-Computer Redundancy:** Ensure continuity via backup systems.
 - **Triple Modular Redundancy (TMR):** Voting logic to mask errors in critical components.
- **SRAM Micro-Locking Mitigation:**
 - Detect errors in SRAM data areas and initiate automatic recovery.
- **System-Level Fault Monitoring:**
 - Real-time bus data monitoring to detect anomalies (e.g., overcurrent, SEL).
 - Automatic reset, power cycling, or isolation of faulty onboard-units.

4.2 Cross-Layer Hybrid Fault-Tolerant Technology

- Cross layer software fault-tolerant architecture.



4.2 Cross-Layer Hybrid Fault-Tolerant Technology

- **Objective:** Balance performance and reliability in harsh space environments.
- **Layered Architecture:**
 - **Application Layer:**
 - Lightweight error detection using invariant assertions.
 - Example: Algorithmic checks for data consistency.
 - **Instruction Layer:**
 - Time/space redundancy for error correction.
 - Example: Re-executing instructions on error detection.
 - **System Layer:**
 - **Heartbeat Monitoring:** High-reliability units send periodic status signals.
 - Example: Confirming CPU health via watchdog signals.
 - **Module Layer:**
 - Secure storage of error logs and recovery data.
 - Example: Trusted storage for fault recovery parameters.

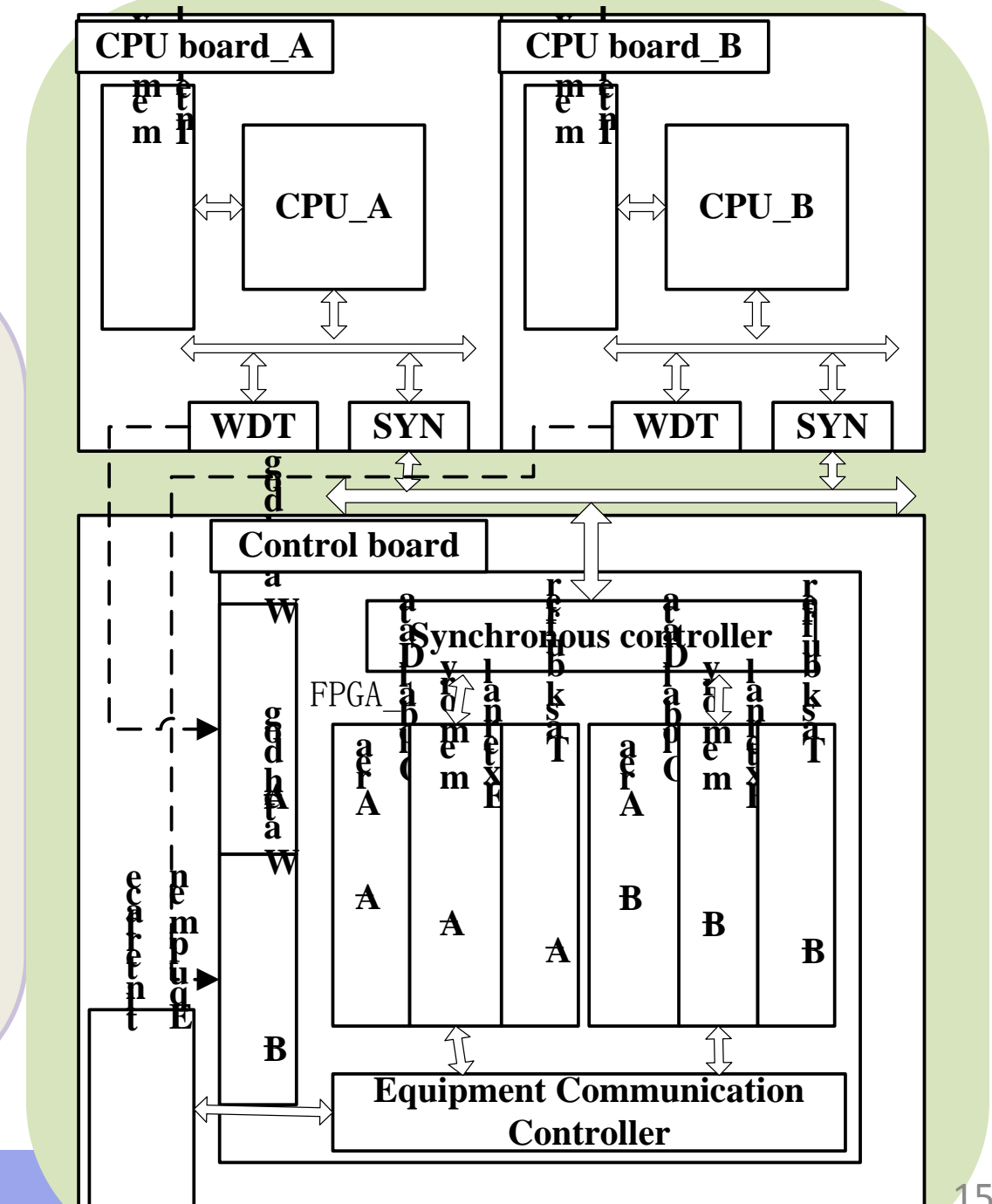
4.3 Radiation-Resistant Application Hardening

- **Single-Event Effects (SEE) Mitigation:**
 - **Watchdog Circuits:** Detect and recover from transient faults.
 - **Redundancy + EDAC:** Protect digital interfaces (e.g., TMR for memory modules).
 - **Current Limiting:** Prevent Single-Event Burnout (SEB) in power terminals.
- **Single-Event Latchup (SEL) Prevention:**
 - Real-time current monitoring and power cutoff.
 - Anti-latchup circuits for critical components.
- **Total Ionizing Dose (TID) Mitigation:**
 - Component layout optimization and localized shielding.

4.3 Radiation-Resistant Application Hardening

Case Study: Dual-redundant Fault-Tolerant System

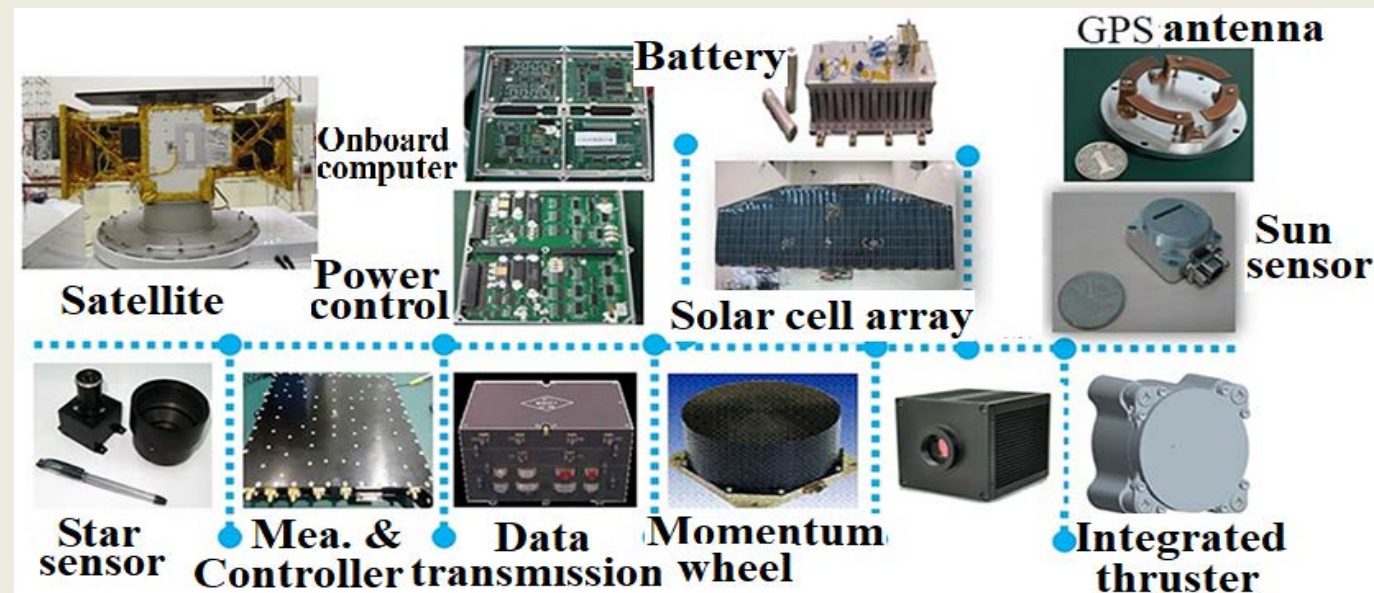
- **Design:**
 - Two redundant CPU boards + control board.
 - TMR for FLASH/SRAM storage modules.
- **Performance:**
 - SEU rate in LEO: $\sim 10^{-7}/(\text{bit}\cdot\text{day})$.
 - TMR improves FLASH reliability by $10^6 \times$ in daily operation.



5. Typical Application Case

5.1 COTS Components Integrated into a Satellite

- **Key COTS Components:**
 - Industrial-grade computers, Li-ion batteries, monocrystalline silicon solar cells.
 - Magnetometers, industrial cameras, measurement/control modules, data transmission modules.
- **Design Philosophy:**
 - Selected for **stable performance, low power consumption, and interface compatibility.**



5.2 COTS Selection and Validation Requirement Analysis

- **Supplier and Product Screening:**
 - Evaluated 25 advanced industrial technologies and 18 new product types.
 - Conducted **200+ tests** on newly selected COTS components.
- **Targeted Testing:**
 - **Space Environment Adaptability:** Radiation, thermal vacuum, mechanical stress.
 - **Specialized Validation:** Error Detection and Correction (EDAC), dual-system redundancy.

5.3 Board-Level Validation Tests

- **Total Ionizing Dose (TID) Test:**
 - 4 multi-channel switches damaged → replaced with radiation-tested alternatives.
- **Other Tests:**
 - All interface, functionality, and performance tests passed.
 - Early failures and defective components eliminated through pre-screening.

Validation Category	Test Items	Objective
Space environment adaptability assessment	Total Ionizing Dose (TID) Test	Identify weak components under radiation.
	Single-Event Test	Validate the computer's ability to resist SEE .
Special validation test	EDAC (FPGA-Based) Test	Verify error detection/correction capabilities.
	Flash Fault Tolerance Test	Assess Flash memory reliability under faults.
	Dual onboard-units Switching Test	Validate redundancy and autonomous switching logic.
Acceptance level/qualification level environmental testing	Mechanical Testing	Confirm structural integrity under vibration/shock.
	Thermal Cycling Test	Validate manufacturing processes and identify early failures.

5.4 COTS In-Orbit Performance

- **Successful Operation:**
 - Satellite has functioned normally for **over 2 years** in orbit.
 - Validated through **ground tests, EMC, thermal, and magnetic property tests.**
- **Key Achievement:**
 - COTS components met mission requirements, demonstrating cost-effectiveness and reliability.

6. Summary

Feasibility of COTS in Space: Success hinges on comprehensive strategies for selection, validation, and usage.

- **Selection Strategy:**
 - Align with mission requirements (orbit, lifespan, reliability).
 - Evaluate 8 critical product criteria (e.g., functional performance, radiation tolerance).
 - Prioritize suppliers using 5 key factors (cost, stable supply, process stability).
- **Application Validation:**
 - Focus on radiation performance for mature COTS components.
 - Integrate board-level validation (e.g., thermal cycling, EMC tests) with system-level requirements.
- **Usage Hardening (Redundancy & Fault Tolerance) :**
 - Implement dual-computer backup, TMR, and EDAC for critical systems.
 - Optimize application hardening (e.g., current limiting, SEL protection).



Thank you for your attention

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